

Title (en)
HOT MELT ADHESIVE COMPOSITIONS

Title (de)
HEISSSCHMELZKLEBSTOFFZUSAMMENSETZUNGEN

Title (fr)
COMPOSITIONS ADHESIVES THERMOFUSIBLES

Publication
EP 0957147 A4 20000913 (EN)

Application
EP 98900677 A 19980121

Priority
• JP 9800211 W 19980121
• JP 1711097 A 19970130

Abstract (en)
[origin: EP0957147A1] A hot-melt adhesive composition comprises 100 parts by weight of a tackifier (B), and 1 to 900 parts by weight of an alpha-olefin/aromatic vinyl compound random copolymer (C). A hot-melt adhesive composition comprises 100 parts by weight of a base polymer (A), 1 to 900 parts by weight of component (B), and 1 to 1,000 parts by weight of component (C). A hot-melt adhesive composition comprises 100 parts by weight of component (A), 10 to 300 parts by weight of component (B), and 10 to 400 parts by weight of component (C). The component (A) is preferably at least one polymer selected from the group consisting of a polyolefin (a-1), a polar group containing polymer (a-2) and an aromatic vinyl compound/conjugated diene copolymer (a-3). These hot-melt adhesive compositions exhibit excellent adhesive strength and can be used as an adhesive for styrene resins.

IPC 1-7
C09J 123/00; C09J 201/00; C09J 109/06; C09J 153/02; C09J 125/00

IPC 8 full level
C09J 109/06 (2006.01); **C09J 123/08** (2006.01); **C09J 125/02** (2006.01); **C09J 125/08** (2006.01); **C09J 151/06** (2006.01); **C09J 153/00** (2006.01); **C09J 153/02** (2006.01); C08L 23/02 (2006.01); C08L 23/06 (2006.01); C08L 23/08 (2006.01); C08L 53/02 (2006.01); C08L 91/06 (2006.01)

CPC (source: EP KR US)
C09J 109/06 (2013.01 - EP US); **C09J 123/00** (2013.01 - KR); **C09J 123/0838** (2013.01 - EP US); **C09J 125/02** (2013.01 - EP US); **C09J 125/08** (2013.01 - EP US); **C09J 151/06** (2013.01 - EP US); **C09J 153/00** (2013.01 - EP US); **C09J 153/005** (2013.01 - EP US); **C09J 153/02** (2013.01 - EP US); **C09J 153/025** (2013.01 - EP US); C08L 23/06 (2013.01 - EP US); C08L 23/0838 (2013.01 - EP US); C08L 53/02 (2013.01 - EP US); C08L 91/06 (2013.01 - EP US); C08L 2666/02 (2013.01 - EP US); C08L 2666/04 (2013.01 - EP US); C08L 2666/24 (2013.01 - EP US); C08L 2666/28 (2013.01 - EP US); Y10S 526/935 (2013.01 - EP US)

Citation (search report)
• [XY] EP 0478800 A1 19920408 - MITSUI PETROCHEMICAL IND [JP]
• [T] EP 0896044 A1 19990210 - MITSUI CHEMICALS INC [JP]
• [Y] DATABASE WPI Derwent World Patents Index; AN 1989-204352, XP002139124
• [T] PATENT ABSTRACTS OF JAPAN vol. 1997, no. 10 31 October 1997 (1997-10-31)
• See references of WO 9833861A1

Cited by
EP1108771A3; EP1905491A1; EP3848428A4; US7495048B2; US6858667B1; WO2004033550A1

Designated contracting state (EPC)
DE FR GB IT NL

DOCDB simple family (publication)
EP 0957147 A1 19991117; **EP 0957147 A4 20000913**; **EP 0957147 B1 20040331**; AU 5574898 A 19980825; AU 733854 B2 20010531; CA 2278736 A1 19980806; CN 1104480 C 20030402; CN 1244889 A 20000216; DE 69822797 D1 20040506; DE 69822797 T2 20050310; ID 21997 A 19990819; KR 100386372 B1 20030602; KR 20000070535 A 20001125; TW 513478 B 20021211; US 6235818 B1 20010522; WO 9833861 A1 19980806

DOCDB simple family (application)
EP 98900677 A 19980121; AU 5574898 A 19980121; CA 2278736 A 19980121; CN 98802073 A 19980121; DE 69822797 T 19980121; ID 990773 A 19980121; JP 9800211 W 19980121; KR 19997006780 A 19990727; TW 87101033 A 19980126; US 35550499 A 19990729